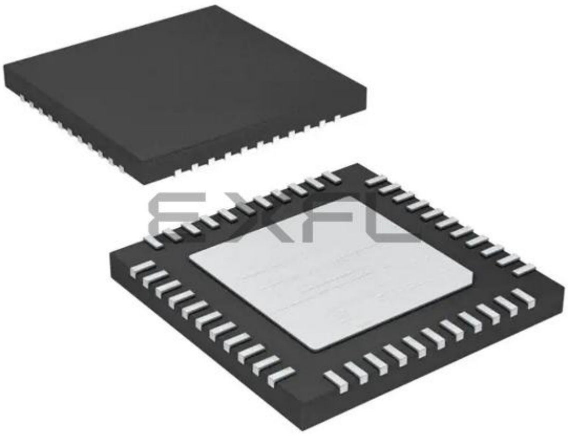
Microchip Technology - DSPIC33EP512GP504T-E/ML Datasheet



What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

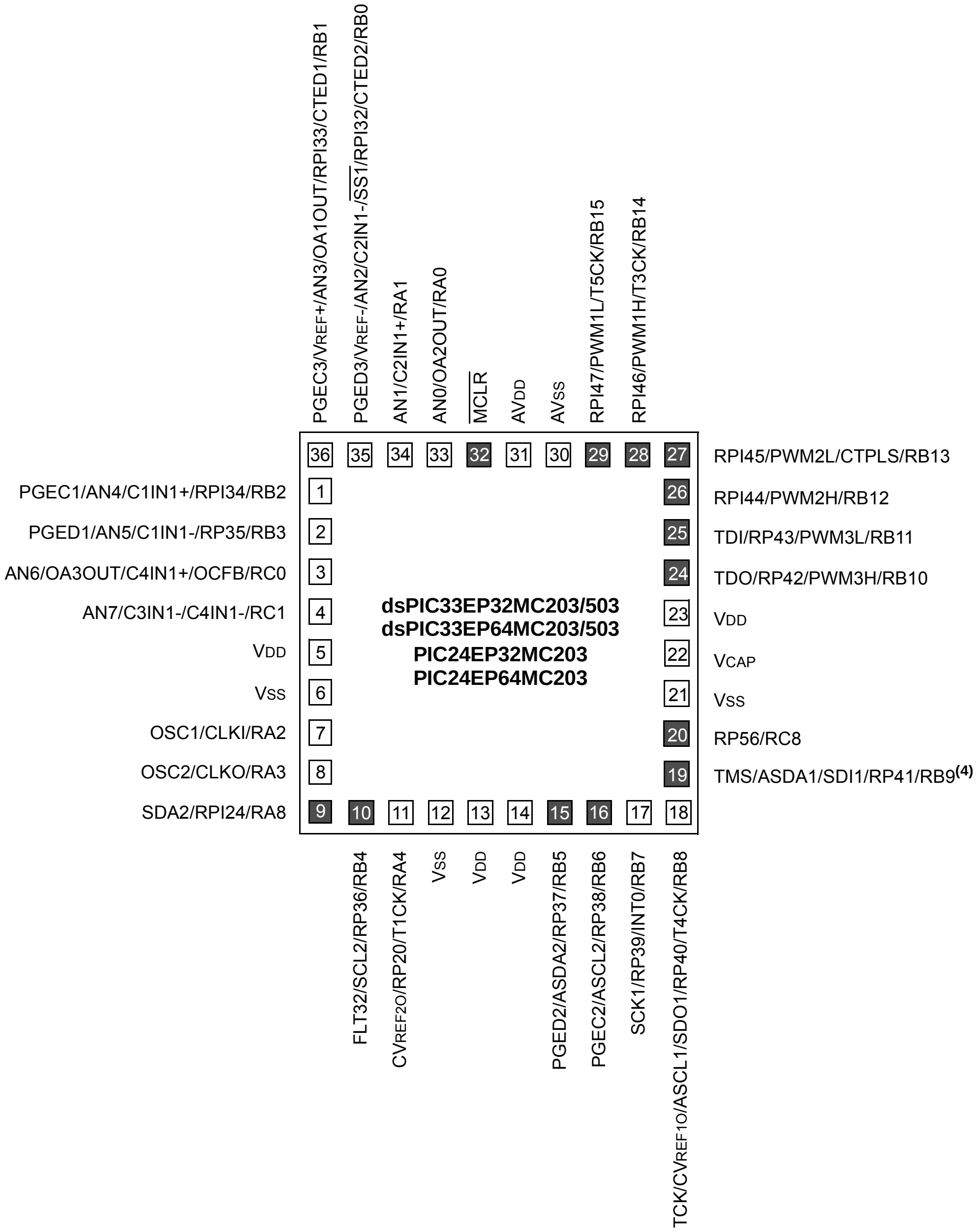
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	35
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep512gp504t-e-ml

Pin Diagrams (Continued)

36-Pin VTLA(1,2,3)

■ = Pins are up to 5V tolerant



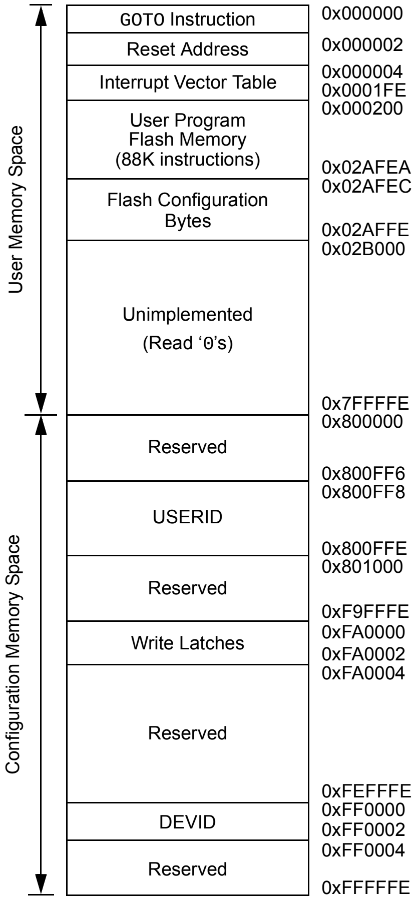
Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

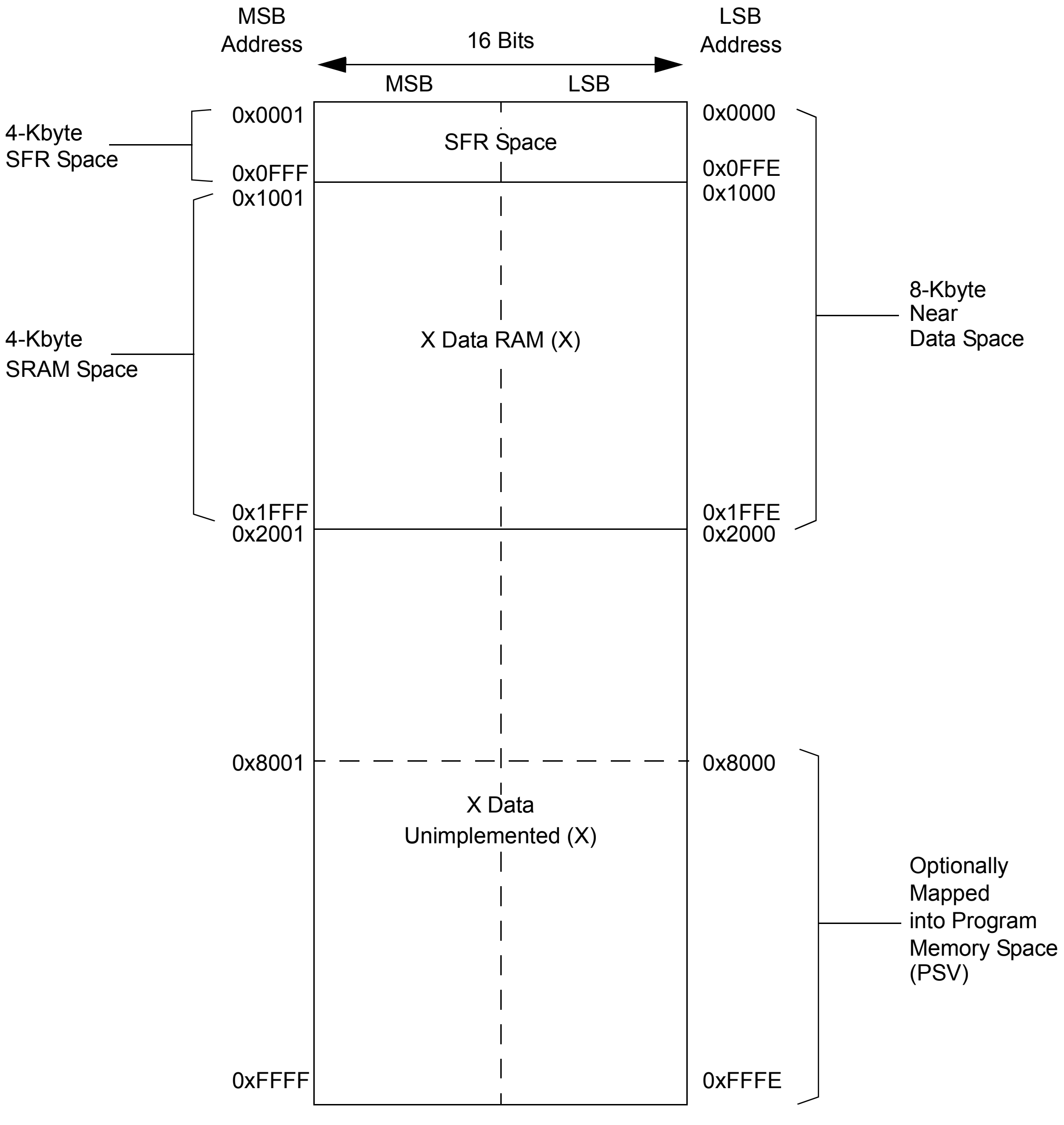
4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

FIGURE 4-4: PROGRAM MEMORY MAP FOR dsPIC33EP256GP50X, dsPIC33EP256MC20X/50X AND PIC24EP256GP/MC20X DEVICES



Note: Memory areas are not shown to scale.

FIGURE 4-12: DATA MEMORY MAP FOR PIC24EP32GP/MC20X/50X DEVICES



Note: Memory areas are not shown to scale.

TABLE 4-9: INPUT CAPTURE 1 THROUGH INPUT CAPTURE 4 REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
IC1CON1	0140	—	—	ICSIDL	ICTSEL<2:0>			—	—	—	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			`0000`
IC1CON2	0142	—	—	—	—	—	—	—	IC32	ICTRIG	TRIGSTAT	—	SYNCSEL<4:0>					`000D`
IC1BUF	0144	Input Capture 1 Buffer Register																`xxxx`
IC1TMR	0146	Input Capture 1 Timer																`0000`
IC2CON1	0148	—	—	ICSIDL	ICTSEL<2:0>			—	—	—	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			`0000`
IC2CON2	014A	—	—	—	—	—	—	—	IC32	ICTRIG	TRIGSTAT	—	SYNCSEL<4:0>					`000D`
IC2BUF	014C	Input Capture 2 Buffer Register																`xxxx`
IC2TMR	014E	Input Capture 2 Timer																`0000`
IC3CON1	0150	—	—	ICSIDL	ICTSEL<2:0>			—	—	—	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			`0000`
IC3CON2	0152	—	—	—	—	—	—	—	IC32	ICTRIG	TRIGSTAT	—	SYNCSEL<4:0>					`000D`
IC3BUF	0154	Input Capture 3 Buffer Register																`xxxx`
IC3TMR	0156	Input Capture 3 Timer																`0000`
IC4CON1	0158	—	—	ICSIDL	ICTSEL<2:0>			—	—	—	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			`0000`
IC4CON2	015A	—	—	—	—	—	—	—	IC32	ICTRIG	TRIGSTAT	—	SYNCSEL<4:0>					`000D`
IC4BUF	015C	Input Capture 4 Buffer Register																`xxxx`
IC4TMR	015E	Input Capture 4 Timer																`0000`

Legend: x = unknown value on Reset, — = unimplemented, read as ‘`0`’. Reset values are shown in hexadecimal.

TABLE 4-27: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP FOR dsPIC33EPXXXGP/MC204/504 AND PIC24EPXXXGP/MC204 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPOR0	0680	—	—	RP35R<5:0>						—	—	RP20R<5:0>						`0000`
RPOR1	0682	—	—	RP37R<5:0>						—	—	RP36R<5:0>						`0000`
RPOR2	0684	—	—	RP39R<5:0>						—	—	RP38R<5:0>						`0000`
RPOR3	0686	—	—	RP41R<5:0>						—	—	RP40R<5:0>						`0000`
RPOR4	0688	—	—	RP43R<5:0>						—	—	RP42R<5:0>						`0000`
RPOR5	068A	—	—	RP55R<5:0>						—	—	RP54R<5:0>						`0000`
RPOR6	068C	—	—	RP57R<5:0>						—	—	RP56R<5:0>						`0000`

Legend: — = unimplemented, read as ‘`0`’. Reset values are shown in hexadecimal.

TABLE 4-28: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP FOR dsPIC33EPXXXGP/MC206/506 AND PIC24EPXXXGP/MC206 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPOR0	0680	—	—	RP35R<5:0>						—	—	RP20R<5:0>						`0000`
RPOR1	0682	—	—	RP37R<5:0>						—	—	RP36R<5:0>						`0000`
RPOR2	0684	—	—	RP39R<5:0>						—	—	RP38R<5:0>						`0000`
RPOR3	0686	—	—	RP41R<5:0>						—	—	RP40R<5:0>						`0000`
RPOR4	0688	—	—	RP43R<5:0>						—	—	RP42R<5:0>						`0000`
RPOR5	068A	—	—	RP55R<5:0>						—	—	RP54R<5:0>						`0000`
RPOR6	068C	—	—	RP57R<5:0>						—	—	RP56R<5:0>						`0000`
RPOR7	068E	—	—	RP97R<5:0>						—	—	—	—	—	—	—	—	`0000`
RPOR8	0690	—	—	RP118R<5:0>						—	—	—	—	—	—	—	—	`0000`
RPOR9	0692	—	—	—	—	—	—	—	—	—	—	RP120R<5:0>						`0000`

Legend: — = unimplemented, read as ‘`0`’. Reset values are shown in hexadecimal.

REGISTER 8-14: DMAPPS: DMA PING-PONG STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	PPST3	PPST2	PPST1	PPST0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-4 **Unimplemented:** Read as ‘0’

bit 3 **PPST3:** DMA Channel 3 Ping-Pong Mode Status Flag bit
1 = DMASTB3 register is selected
0 = DMASTA3 register is selected

bit 2 **PPST2:** DMA Channel 2 Ping-Pong Mode Status Flag bit
1 = DMASTB2 register is selected
0 = DMASTA2 register is selected

bit 1 **PPST1:** DMA Channel 1 Ping-Pong Mode Status Flag bit
1 = DMASTB1 register is selected
0 = DMASTA1 register is selected

bit 0 **PPST0:** DMA Channel 0 Ping-Pong Mode Status Flag bit
1 = DMASTB0 register is selected
0 = DMASTA0 register is selected

12.0 TIMER1

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Timers"** (DS70362) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Timer1 module is a 16-bit timer that can operate as a free-running interval timer/counter.

The Timer1 module has the following unique features over other timers:

- Can be operated in Asynchronous Counter mode from an external clock source
- The external clock input (T1CK) can optionally be synchronized to the internal device clock and the clock synchronization is performed after the prescaler

A block diagram of Timer1 is shown in Figure 12-1.

The Timer1 module can operate in one of the following modes:

- Timer mode
- Gated Timer mode
- Synchronous Counter mode
- Asynchronous Counter mode

In Timer and Gated Timer modes, the input clock is derived from the internal instruction cycle clock (FCY). In Synchronous and Asynchronous Counter modes, the input clock is derived from the external clock input at the T1CK pin.

The Timer modes are determined by the following bits:

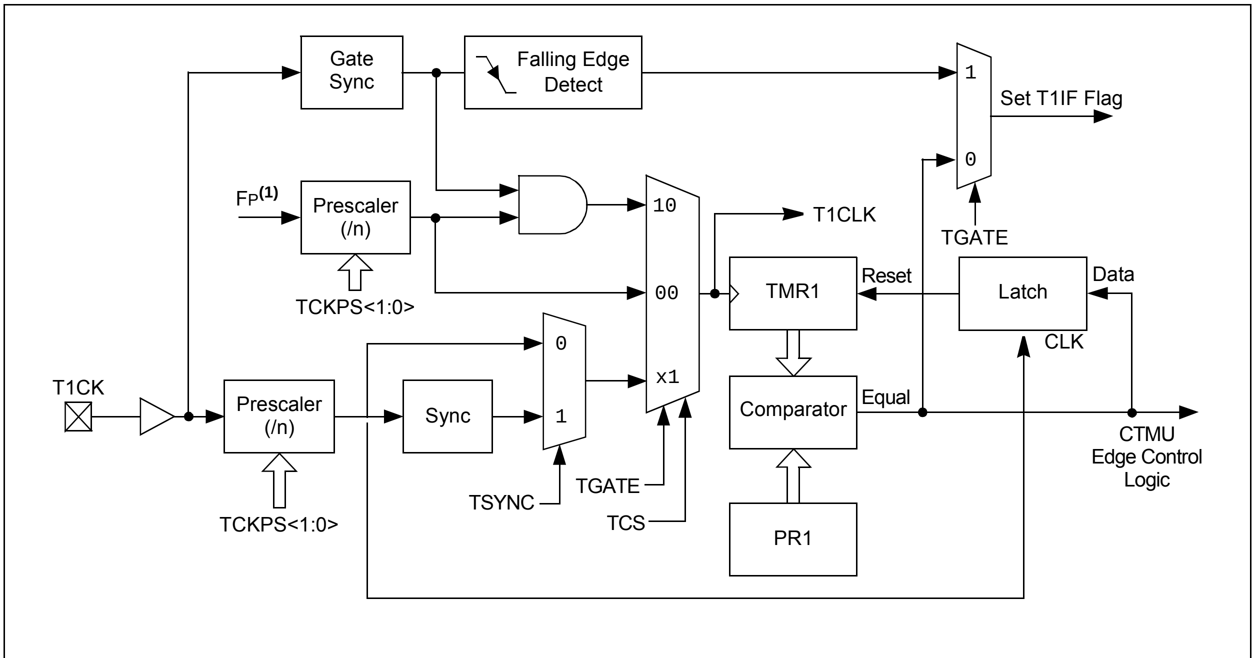
- Timer Clock Source Control bit (TCS): T1CON<1>
- Timer Synchronization Control bit (TSYNC): T1CON<2>
- Timer Gate Control bit (TGATE): T1CON<6>

Timer control bit setting for different operating modes are given in the Table 12-1.

TABLE 12-1: TIMER MODE SETTINGS

Mode	TCS	TGATE	TSYNC
Timer	0	0	x
Gated Timer	0	1	x
Synchronous Counter	1	x	1
Asynchronous Counter	1	x	0

FIGURE 12-1: 16-BIT TIMER1 MODULE BLOCK DIAGRAM



Note 1: FP is the peripheral clock.

NOTES:

15.1 Output Compare Resources

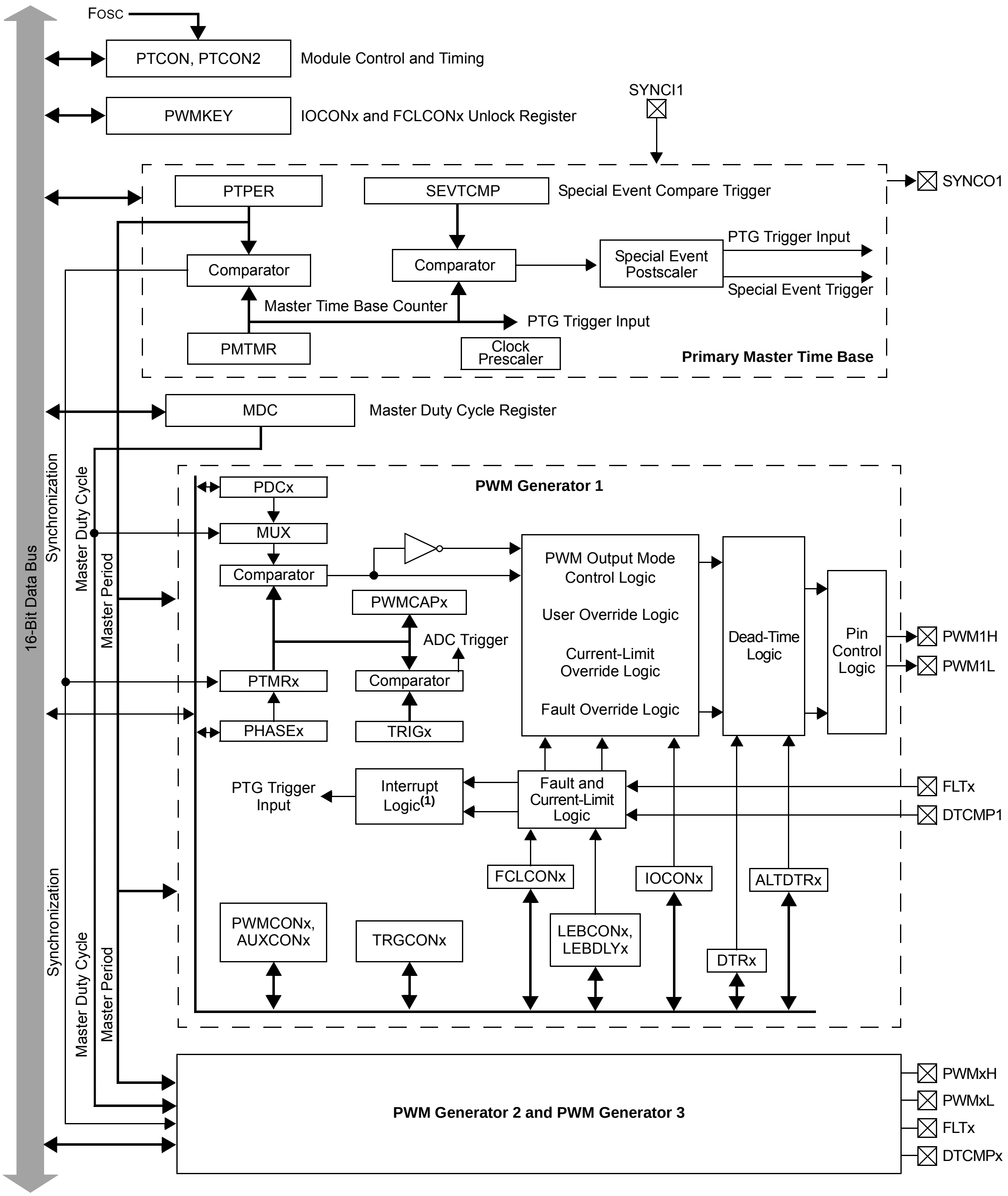
Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser:
http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

15.1.1 KEY RESOURCES

- **"Output Compare"** (DS70358) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

FIGURE 16-2: HIGH-SPEED PWMx MODULE REGISTER INTERCONNECTION DIAGRAM



Note 1: The PWM interrupts are generated by logically ORing the FLTSTAT, CLSTAT and TRGSTAT status bits for the given PWM generator. Refer to the "*dsPIC33/PIC24 Family Reference Manual*", **"High-Speed PWM"** (DS70645) for more information.

REGISTER 19-3: I2CxMSK: I2Cx SLAVE MODE ADDRESS MASK REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	AMSK9	AMSK8
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
AMSK7	AMSK6	AMSK5	AMSK4	AMSK3	AMSK2	AMSK1	AMSK0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-10 **Unimplemented:** Read as ‘`0`’

bit 9-0 **AMSK<9:0>:** Address Mask Select bits

For 10-Bit Address:
`1` = Enables masking for bit Ax of incoming message address; bit match is not required in this position
`0` = Disables masking for bit Ax; bit match is required in this position

For 7-Bit Address (I2CxMSK<6:0> only):
`1` = Enables masking for bit Ax + 1 of incoming message address; bit match is not required in this position
`0` = Disables masking for bit Ax + 1; bit match is required in this position

21.5 ECAN Message Buffers

ECAN Message Buffers are part of RAM memory. They are not ECAN Special Function Registers. The user application must directly write into the RAM area that is configured for ECAN Message Buffers. The location and size of the buffer area is defined by the user application.

BUFFER 21-1: ECAN™ MESSAGE BUFFER WORD 0

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	SID10	SID9	SID8	SID7	SID6
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SID5	SID4	SID3	SID2	SID1	SID0	SRR	IDE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12-2 **SID<10:0>:** Standard Identifier bits

bit 1 **SRR:** Substitute Remote Request bit

When IDE = 0:
1 = Message will request remote transmission
0 = Normal message

When IDE = 1:
The SRR bit must be set to ‘1’.

bit 0 **IDE:** Extended Identifier bit

1 = Message will transmit Extended Identifier
0 = Message will transmit Standard Identifier

BUFFER 21-2: ECAN™ MESSAGE BUFFER WORD 1

U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	—	EID17	EID16	EID15	EID14
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID13	EID12	EID11	EID10	EID9	EID8	EID7	EID6
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-12 **Unimplemented:** Read as ‘0’

bit 11-0 **EID<17:6>:** Extended Identifier bits

REGISTER 23-2: AD1CON2: ADC1 CONTROL REGISTER 2 (CONTINUED)

bit 1	**BUFM:** Buffer Fill Mode Select bit `1` = Starts the buffer filling the first half of the buffer on the first interrupt and the second half of the buffer on next interrupt `0` = Always starts filling the buffer from the start address.
bit 0	**ALTS:** Alternate Input Sample Mode Select bit `1` = Uses channel input selects for Sample MUXA on first sample and Sample MUXB on next sample `0` = Always uses channel input selects for Sample MUXA

24.0 PERIPHERAL TRIGGER GENERATOR (PTG) MODULE

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Peripheral Trigger Generator (PTG)"** (DS70669) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

24.1 Module Introduction

The Peripheral Trigger Generator (PTG) provides a means to schedule complex high-speed peripheral operations that would be difficult to achieve using software. The PTG module uses 8-bit commands, called "Steps", that the user writes to the PTG Queue registers (PTGQUE0-PTGQUE7), which perform operations, such as wait for input signal, generate output trigger and wait for timer.

The PTG module has the following major features:

- Multiple clock sources
- Two 16-bit general purpose timers
- Two 16-bit general limit counters
- Configurable for rising or falling edge triggering
- Generates processor interrupts to include:
  - Four configurable processor interrupts
  - Interrupt on a Step event in Single-Step mode
  - Interrupt on a PTG Watchdog Timer time-out
- Able to receive trigger signals from these peripherals:
  - ADC
  - PWM
  - Output Compare
  - Input Capture
  - Op Amp/Comparator
  - INT2
- Able to trigger or synchronize to these peripherals:
  - Watchdog Timer
  - Output Compare
  - Input Capture
  - ADC
  - PWM
  - Op Amp/Comparator

29.6 MPLAB X SIM Software Simulator

The MPLAB X SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB X SIM Software Simulator fully supports symbolic debugging using the MPLAB XC Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

29.7 MPLAB REAL ICE In-Circuit Emulator System

The MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs all 8, 16 and 32-bit MCU, and DSC devices with the easy-to-use, powerful graphical user interface of the MPLAB X IDE.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ-11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB X IDE. MPLAB REAL ICE offers significant advantages over competitive emulators including full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, logic probes, a ruggedized probe interface and long (up to three meters) interconnection cables.

29.8 MPLAB ICD 3 In-Circuit Debugger System

The MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost-effective, high-speed hardware debugger/programmer for Microchip Flash DSC and MCU devices. It debugs and programs PIC Flash microcontrollers and dsPIC DSCs with the powerful, yet easy-to-use graphical user interface of the MPLAB IDE.

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

29.9 PICkit 3 In-Circuit Debugger/ Programmer

The MPLAB PICkit 3 allows debugging and programming of PIC and dsPIC Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB IDE. The MPLAB PICkit 3 is connected to the design engineer's PC using a full-speed USB interface and can be connected to the target via a Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the Reset line to implement in-circuit debugging and In-Circuit Serial Programming™ (ICSP™).

29.10 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at VDDMIN and VDDMAX for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages, and a modular, detachable socket assembly to support various package types. The ICSP cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices, and incorporates an MMC card for file storage and data applications.

30.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X electrical characteristics. Additional information will be provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings(1)

Ambient temperature under bias	-40°C to +125°C
Storage temperature	-65°C to +150°C
Voltage on VDD with respect to VSS	-0.3V to +4.0V
Voltage on any pin that is not 5V tolerant, with respect to VSS(3)	-0.3V to (VDD + 0.3V)
Voltage on any 5V tolerant pin with respect to VSS when VDD ≥ 3.0V(3)	-0.3V to +5.5V
Voltage on any 5V tolerant pin with respect to Vss when VDD < 3.0V(3)	-0.3V to +3.6V
Maximum current out of VSS pin	300 mA
Maximum current into VDD pin(2)	300 mA
Maximum current sunk/sourced by any 4x I/O pin	15 mA
Maximum current sunk/sourced by any 8x I/O pin	25 mA
Maximum current sunk by all ports(2,4)	200 mA

Note 1: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 30-2).

3: See the **“Pin Diagrams”** section for the 5V tolerant pins.

4: Exceptions are: dsPIC33EPXXXGP502, dsPIC33EPXXXMC202/502 and PIC24EPXXXGP/MC202 devices, which have a maximum sink/source capability of 130 mA.

TABLE 30-12: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
DO10	V_{OL}	**Output Low Voltage** 4x Sink Driver Pins(2)	—	—	0.4	V	V_{DD} = 3.3V, I_{OL} ≤ 6 mA, -40°C ≤ T_A ≤ +85°C I_{OL} ≤ 5 mA, +85°C < T_A ≤ +125°C
		Output Low Voltage 8x Sink Driver Pins(3)	—	—	0.4	V	V_{DD} = 3.3V, I_{OL} ≤ 12 mA, -40°C ≤ T_A ≤ +85°C I_{OL} ≤ 8 mA, +85°C < T_A ≤ +125°C
DO20	V_{OH}	**Output High Voltage** 4x Source Driver Pins(2)	2.4	—	—	V	I_{OH} ≥ -10 mA, V_{DD} = 3.3V
		Output High Voltage 8x Source Driver Pins(3)	2.4	—	—	V	I_{OH} ≥ -15 mA, V_{DD} = 3.3V
DO20A	V_{OH1}	**Output High Voltage** 4x Source Driver Pins(2)	1.5(1)	—	—	V	I_{OH} ≥ -14 mA, V_{DD} = 3.3V
			2.0(1)	—	—		I_{OH} ≥ -12 mA, V_{DD} = 3.3V
			3.0(1)	—	—		I_{OH} ≥ -7 mA, V_{DD} = 3.3V
		Output High Voltage 8x Source Driver Pins(3)	1.5(1)	—	—	V	I_{OH} ≥ -22 mA, V_{DD} = 3.3V
			2.0(1)	—	—		I_{OH} ≥ -18 mA, V_{DD} = 3.3V
			3.0(1)	—	—		I_{OH} ≥ -10 mA, V_{DD} = 3.3V

Note 1: Parameters are characterized but not tested.

2: Includes all I/O pins that are not 8x Sink Driver pins (see below).

3: Includes the following pins:
For devices with less than 64 pins: RA3, RA4, RA9, RB<7:15> and RC3
For 64-pin devices: RA4, RA9, RB<7:15>, RC3 and RC15

TABLE 30-13: ELECTRICAL CHARACTERISTICS: BOR

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)(1)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.(2)**	**Typ.**	**Max.**	**Units**	**Conditions**
BO10	V_{BOR}	BOR Event on V_{DD} Transition High-to-Low	2.65	—	2.95	V	V_{DD} **(Notes 2** and **3)**

Note 1: Device is functional at V_{BORMIN} < V_{DD} < V_{DDMIN}, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance.

2: Parameters are for design guidance only and are not tested in manufacturing.

3: The V_{BOR} specification is relative to V_{DD}.

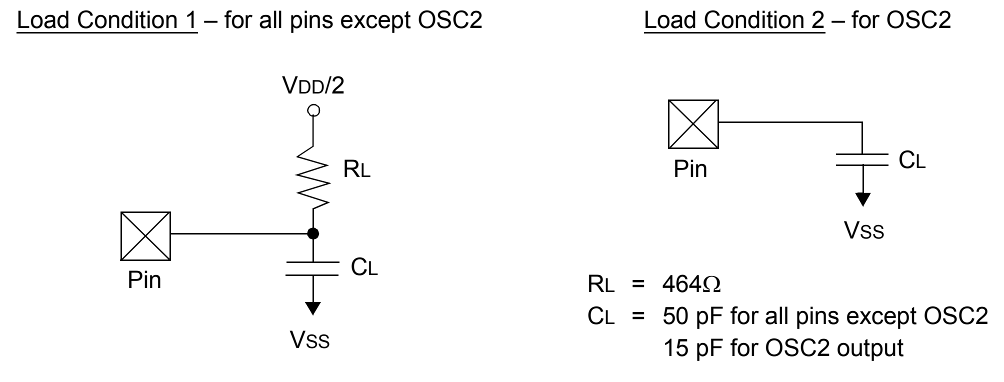
30.2 AC Characteristics and Timing Parameters

This section defines dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X AC characteristics and timing parameters.

TABLE 30-15: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions: 3.0V to 3.6V** **(unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended Operating voltage V_{DD} range as described in **Section 30.1 “DC Characteristics”**.

FIGURE 30-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS



R_L = 464Ω
C_L = 50 pF for all pins except OSC2
15 pF for OSC2 output

TABLE 30-16: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
DO50	C_{OSCO}	OSC2 Pin	—	—	15	pF	In XT and HS modes, when external clock is used to drive OSC1
DO56	C_{IO}	All I/O Pins and OSC2	—	—	50	pF	EC mode
DO58	C_B	SCLx, SDAx	—	—	400	pF	In I^{2}C™ mode

FIGURE 30-34: ECANx MODULE I/O TIMING CHARACTERISTICS

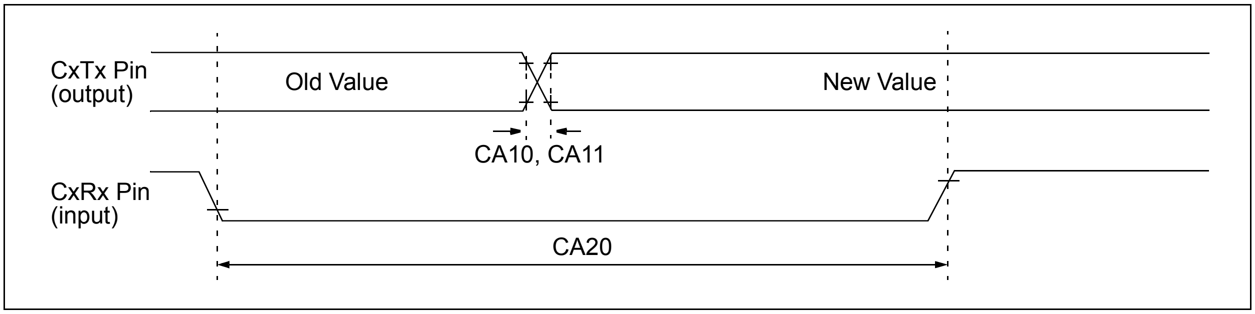


TABLE 30-51: ECANx MODULE I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**[1]	**Min.**	**Typ.**[2]	**Max.**	**Units**	**Conditions**
CA10	TIOF	Port Output Fall Time	—	—	—	ns	See Parameter DO32
CA11	TIOR	Port Output Rise Time	—	—	—	ns	See Parameter DO31
CA20	TCWF	Pulse Width to Trigger CAN Wake-up Filter	120	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 30-35: UARTx MODULE I/O TIMING CHARACTERISTICS

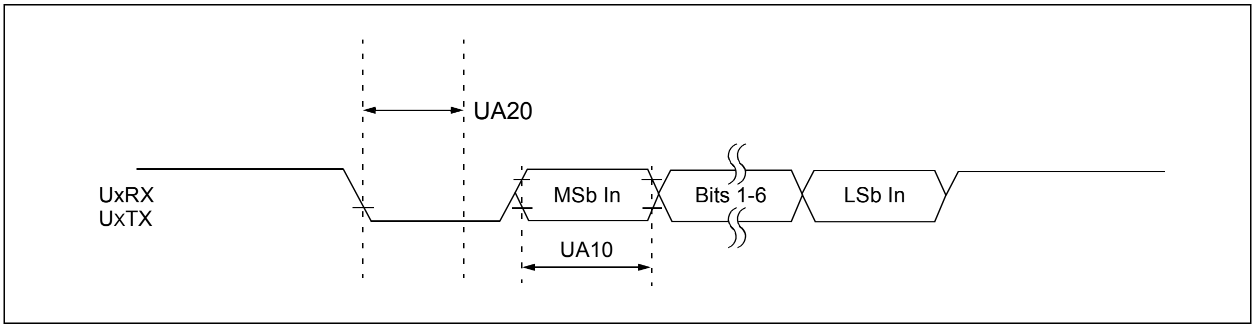


TABLE 30-52: UARTx MODULE I/O TIMING REQUIREMENTS

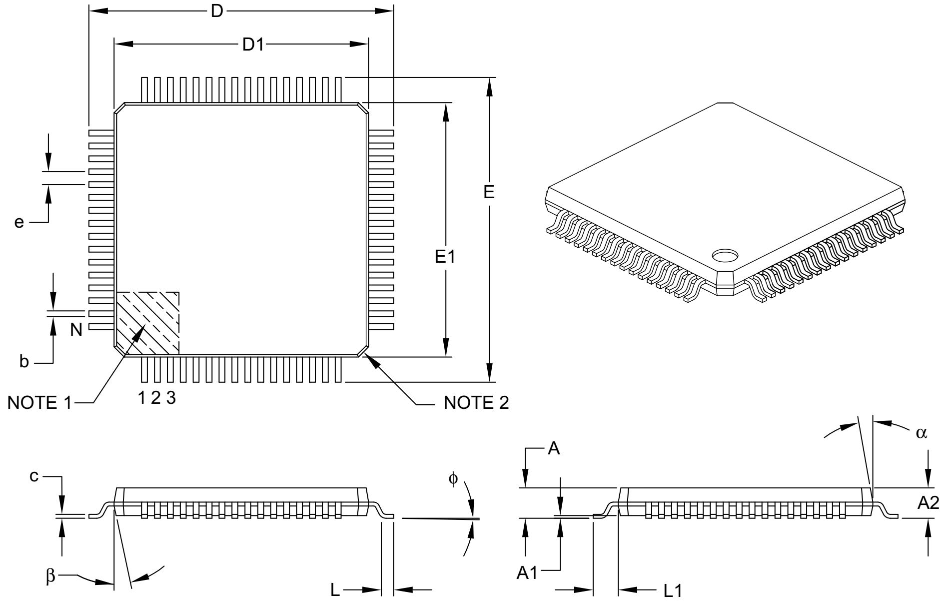
AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C				
Param No.	**Symbol**	**Characteristic**[1]	**Min.**	**Typ.**[2]	**Max.**	**Units**	**Conditions**
UA10	TUABAUD	UARTx Baud Time	66.67	—	—	ns	
UA11	FBAUD	UARTx Baud Frequency	—	—	15	Mbps	
UA20	TCWF	Start Bit Pulse Width to Trigger UARTx Wake-up	500	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N	64		
Lead Pitch	e	0.50 BSC		
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	φ	0°	3.5°	7°
Overall Width	E	12.00 BSC		
Overall Length	D	12.00 BSC		
Molded Package Width	E1	10.00 BSC		
Molded Package Length	D1	10.00 BSC		
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085B